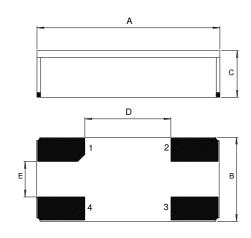


Package & Application informations

Package dimension:

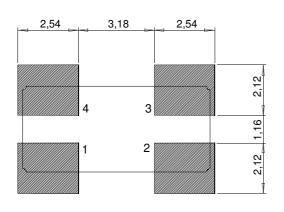


<u>Dimensions</u>: Pin Out:

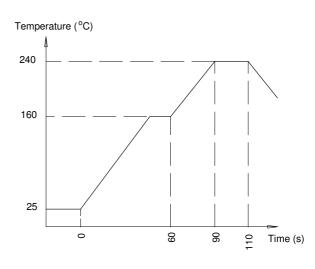
	In.	mm		
A	0.30	7.86 ± 0.2	1	Option: Enable/Disable
В	0.14	3.60 ± 0.2	2	GND
C	0.08	2.00 ± 0.2	3	Output
D	0.15	3.70 ± 0.2	4	Vcc
E	0.06	1.52 ± 0.2		

Recommended solder pad layout & soldering conditions:

Solder pad layout



Soldering conditions



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In accordance with our policy of continuous development and improvement, we reserve the right to modify the design or the specifications of our products without prior notice.

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